1. Part No. Expression:

WAQ7FW201-RA-10

(d)

- (a) (b) (c)
- (e)(f)
- (g)

(a) Series Code

(e) Packaging Code

(b) Dimension Code

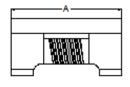
(f) Current Rating Code

(c) Material Code

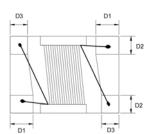
(g) Internal Controlled Number

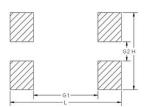
(d) Inductance Code

2. Configuration & Dimensions:







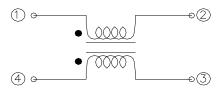


Recommended PCB layout

Unit: mm

Α	В	С	D1	D2	D3	L	Н	G1	G2
4.5±0.2	3.2±0.2	2.8±0.15	0.8±0.2	0.85±0.2	0.6±0.2	5.0 Ref.	3.6 Ref.	3.4 Ref.	1.7 Ref.

3. Schematic:

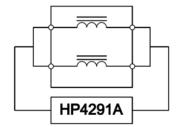


NOTE: Specifications subject to change without notice. Please check our website for latest information.

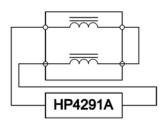


4. Measuring Circuits:

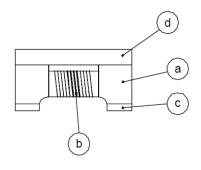
Common mode



Differential mode



5. Material List:



- (a) Core
- (b) Wire
- (c) Terminal
- (d) Upper Plate

6. General Specification:

(a) Reliability test for this part meets AEC-Q200 standard.

(b) Operating Temp.: -40°C to +125°C (Including self - temperature rise).

(c) Storage Temp. : -40°C to +125°C (on board).

(d) Humidity Range: 85 ± 3% RH.

(e) Storage Condition (Component in its packaging)

i) Temperature: Less than 40°C

ii) Humidity: 60% RH

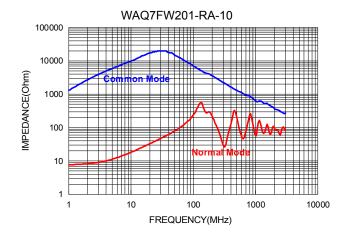
NOTE: Specifications subject to change without notice. Please check our website for latest information.



7. Electrical Characteristics:

	Inductance (uH)+60/-20uH	Test	DCR	Rated	Rated Volt (Vdc)	IR
Part Number		Frequency	(Ω)	Current		(Ω)
		(Hz)	Max.	(mA)		Min.
WAQ7FW201-RA-10	200	0.1V/100K	4.5	100	50	10M

8. Characteristics Curves:



9. Soldering:

Mildly activated rosin fluxes are preferred. Our terminations are suitable for all re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

9-1 Solder Re-flow

Recommended temperature profiles for re-flow soldering in Figure 1.

9-2 Soldering Iron (Figure 2)

Products attachment with soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

Note

- a) Preheat circuit and products to 150°C.
- b) 355°C tip temperature (Max.)
- c) Never contact the ceramic with the iron tip
- d) 1.0mm tip diameter (Max.)
- e) Use a 20 watt soldering iron with tip diameter of 1.0mm
- f) Limit soldering time to 4~5 sec.

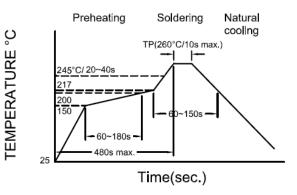


Figure 1. : Re-flow Soldering time 3 times Max.

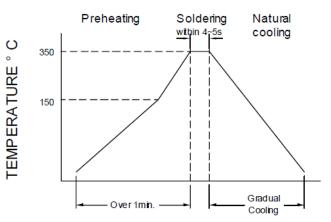
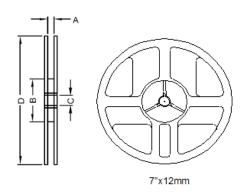
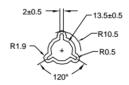


Figure 2. : Iron Soldering time 1 times Max.

10. Packaging Information:

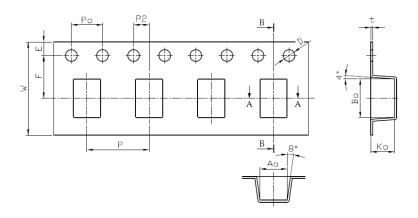
10-1 Reel Dimension





Туре	A(mm)	B(mm)	C(mm)	D(mm)
7"x12mm	13.5±0.5	60.0±2.0	13.5±0.5	178±2.0

10-2 Tape Dimension

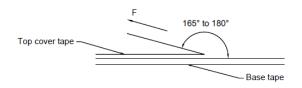


Size	P(mm)	Po(mm)	P2(mm)	Bo(mm)	Ao(mm)	Ko(mm)
Size	8.00±0.10	4.00±0.10	2.00±0.05	4.90±0.10	3.60±0.10	3.00±0.10
WAQ7FW	D(mm)	E(mm)	F(mm)	W(mm)	t(mm)	
WAQTIW	1.05+0.10/-0.00	1.75±0.10	5.50±0.05	12.00±0.10	0.26±0.05	

10-3 Packaging Quantity

Chip Size	WAQ7FW		
Chip/Reel	500		
Inner Box	2,000		
Middle Box	10,000		
Carton	20,000		

10-4 Tearing Off Force



The force for tearing off cover tape is 15 to 80 grams in the arrow direction under the following conditions.

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

Application Notice:

1. Storage Conditions:

To maintain the solderability of terminal electrodes:

- a) Recommended products should be used within 12 months from the time of delivery.
- b) The packaging material should be kept where no chlorine or sulfur exists in the air.

2. Transportation:

- a) Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- b) Vacuum pick up is strongly recommended for individual components.
- c) Bulk handling should ensure that abrasion and mechanical shock are minimized.

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